

# GPU SuperServer SYS-221GE-TNHT-LCC

DP Intel 2U liquid-cooled system with NVIDIA HGX™ H100 4-GPU or H200 4-GPU



More details here

## Key Applications

High Performance Computing, AI/Deep Learning Training, Industrial Automation, Healthcare, Conversational AI, Business Intelligence & Analytics, Drug Discovery, Climate and Weather Modeling, Finance & Economics,

## Key Features

- Highest GPU communication using NVIDIA® NVLINK™
- High density 2U system with NVIDIA® HGX™ H100 4-GPU/H200 4-GPU and 4xPCIe Gen 5 slots;
- 5th/4th Gen Intel® Xeon® Scalable processor support;
- 32 DIMM slots, up to 8TB 3DS ECC RDIMM, DDR5-5600MT/s. Up to 256 GB of memory with speeds of up to 5600 MT/s(1DPC) or 4400 MT/s (2DPC);
- 4 PCIe Gen 5.0 X16 LP;
- Flexible networking options;
- 2 M.2 NVMe for boot drive only
- 4x 2.5" Hot-swap NVMe/SATA3 drive bays;
- Direct-To-Chip Liquid Cooling solution
- 4 heavy duty fans with optimal fan speed control;
- 2x 5250W(1+1) Redundant Power Supplies;

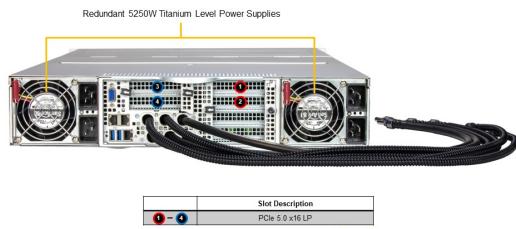


Form Factor	2U Rackmount Enclosure: 437 x 89 x 830.3mm (17.2" x 3.5" x 32.7") Package: (22.5" x 11" x 45.5")
Processor	Dual Socket E (LGA-4677) 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors Up to 56C/112T; Up to 112.5MB Cache per CPU
GPU	Max GPU Count: 4 onboard GPUs Supported GPU: NVIDIA SXM: HGX H100 4-GPU (80GB), HGX H200 4-GPU (141GB) CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect GPU-GPU Interconnect: NVIDIA® NVLink™
System Memory	Slot Count: 32 DIMM slots/16 Channels Max Memory (2DPC): Up to 8TB 5600MT/s ECC DDR5 RDIMM/LRDIMM
Drive Bays Configuration	Default: Total 4 bays • 4 front hot-swap 2.5" NVMe/SATA drive bays
Expansion Slots	PCI-Express (PCIe) Configuration: Default • 4 PCIe 5.0 x16 LP slots M.2: 2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110(default)/2280)
On-Board Devices	Chipset: Intel® C741 Network Connectivity: 2 RJ45 10GbE with Intel® X710-AT2
Input / Output	1 VGA port

(Front View – System)



(Rear View – System)

**System Cooling**

Fans: Up to 4 Fan 8cm Fan(s)  
 Air Shroud: 1 Air Shroud  
 Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)

**Power Supply**

2x 5250W Redundant Titanium Level (96%) power supplies

**System BIOS**

BIOS Type: AMI 32MB SPI Flash EEPROM

**Management**

SuperCloud Composer®; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!

**PC Health Monitoring**

CPU: Monitors for CPU Cores, Chipset Voltages, Memory  
 8+4 Phase-switching voltage regulator  
 FAN: Fans with tachometer monitoring  
 Status monitor for speed control  
 Pulse Width Modulated (PWM) fan connectors  
 Temperature: Monitoring for CPU and chassis environment  
 Thermal Control for fan connectors

**Dimensions and Weight**

Weight: Gross Weight: 86.5 lbs (39.2 kg)  
 Net Weight: 67.5 lbs (30.6 kg)  
 Available Color: Silver Body

**Operating Environment**

Operating Temperature: 10°C to 35°C (50°F to 95°F)  
 Non-operating Temperature: -40°C to 60°C (-40°F to 140°F)  
 Operating Relative Humidity: 8% to 90% (non-condensing)  
 Non-operating Relative Humidity: 5% to 95% (non-condensing)

**Motherboard**

[\*\*Super X13DEG-R\*\*](#)

**Chassis**

**CSE-228G2TS-R5K25P**